

SEMiX302GB12Vs



SEMiX® 2s

SEMiX302GB12Vs

Features

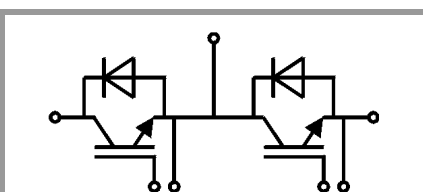
- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^{\circ}\text{C}$ max.
- Product reliability results are valid for $T_J=150^{\circ}\text{C}$
- Dynamic values apply to the following combination of resistors:
 $R_{Gon,main} = 0,5 \Omega$
 $R_{Goff,main} = 0,5 \Omega$
 $R_{G,X} = 2,2 \Omega$
 $R_{E,X} = 0,5 \Omega$



GB

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 175 °C	T _c = 25 °C	448	A
		T _c = 80 °C	342	A
I _{Cnom}			300	A
I _{CRM}	I _{CRM} = 3xI _{Cnom}		900	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 720 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 125 °C	10	μs
T _j			-40 ... 175	°C
Inverse diode				
I _F	T _j = 175 °C	T _c = 25 °C	356	A
		T _c = 80 °C	266	A
I _{Fnom}			300	A
I _{FRM}	I _{FRM} = 3xI _{Fnom}		900	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		1620	A
T _j			-40 ... 175	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C		600	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50Hz, t = 1 min		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 300 A	T _j = 25 °C		1.75	2.2	V
	V _{GE} = 15 V chipelevel	T _j = 150 °C		2.2	2.5	V
V _{CE0}		T _j = 25 °C		0.94	1.04	V
		T _j = 150 °C		0.88	0.98	V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		2.7	3.9	mΩ
		T _j = 150 °C		4.4	5.1	mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 12 mA		5.5	6	6.5	V
I _{CES}	V _{GE} = 0 V	T _j = 25 °C		0.1	0.3	mA
	V _{CE} = 1200 V	T _j = 150 °C				mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		18.0		nF
C _{oes}		f = 1 MHz		1.77		nF
C _{res}		f = 1 MHz		1.77		nF
Q _G	V _{GE} = - 8 V...+ 15 V			3300		nC
R _{Gint}	T _j = 25 °C			2.50		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		424		ns
t _r	I _C = 300 A	T _j = 150 °C		64		ns
E _{on}	V _{GE} = ±15 V	T _j = 150 °C		37.3		mJ
t _{d(off)}	R _{G on} = 1.9 Ω	T _j = 150 °C		619		ns
t _f	R _{G off} = 1.9 Ω	T _j = 150 °C		90		ns
E _{off}	di/dt _{on} = 5700 A/μs	T _j = 150 °C		36.1		mJ
	di/dt _{off} = 3000 A/μs					
	du/dt _{off} = 6500 V/μs					
R _{th(j-c)}	per IGBT				0.1	K/W

SEMiX302GB12Vs



SEMiX® 2s

SEMiX302GB12Vs

Features

- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

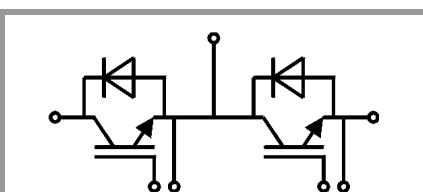
Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^{\circ}\text{C}$ max.
- Product reliability results are valid for $T_j=150^{\circ}\text{C}$
- Dynamic values apply to the following combination of resistors:
 $R_{Gon,main} = 0,5 \Omega$
 $R_{Goff,main} = 0,5 \Omega$
 $R_{G,X} = 2,2 \Omega$
 $R_{E,X} = 0,5 \Omega$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 300 A V _{GE} = 0 V chip	T _j = 25 °C		2.1	2.46	V
		T _j = 150 °C		2.1	2.4	V
V _{F0}		T _j = 25 °C	1.1	1.3	1.5	V
		T _j = 150 °C	0.7	0.9	1.1	V
r _F		T _j = 25 °C	2.2	2.8	3.2	mΩ
		T _j = 150 °C	3.5	3.9	4.3	mΩ
I _{RRM}	I _F = 300 A	T _j = 150 °C		318		A
Q _{rr}	di/dt _{off} = 5800 A/μs	T _j = 150 °C		54		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _j = 150 °C		21.8		mJ
R _{th(j-c)}	per diode				0.17	K/W
Module						
L _{CE}				18		nH
R _{CC'+EE'}	res., terminal-chip	T _C = 25 °C		0.7		mΩ
		T _C = 125 °C		1		mΩ
R _{th(c-s)}	per module			0.045		K/W
M _s	to heat sink (M5)		3		5	Nm
M _t		to terminals (M6)	2.5		5	Nm
						Nm
w					250	g
Temperatur Sensor						
R ₁₀₀	T _c =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω
B _{100/125}	R _(T) =R ₁₀₀ exp[B _{100/125} (1/T-1/T ₁₀₀)]; T[K];			3550 ±2%		K



GB

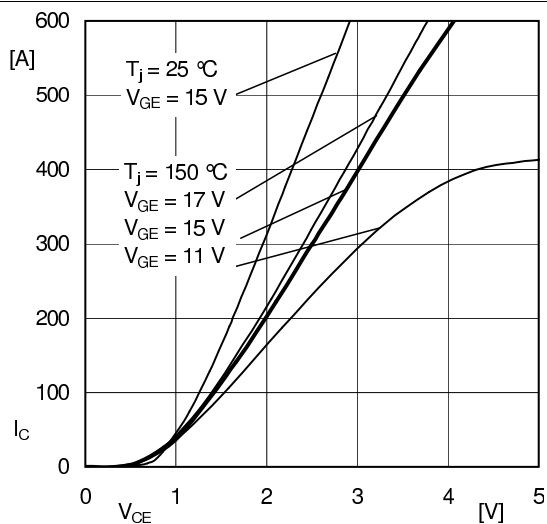


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + E_{E'}$

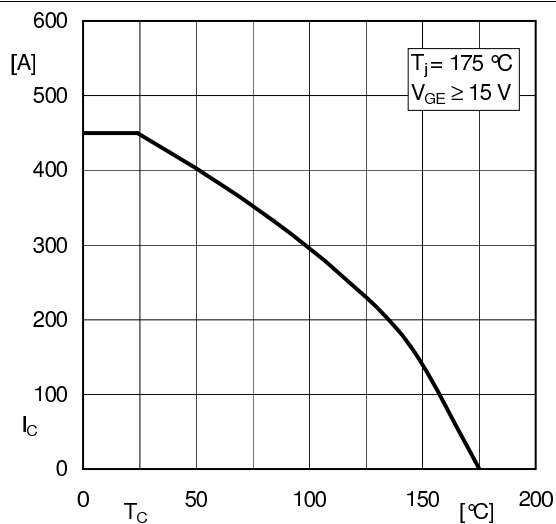


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

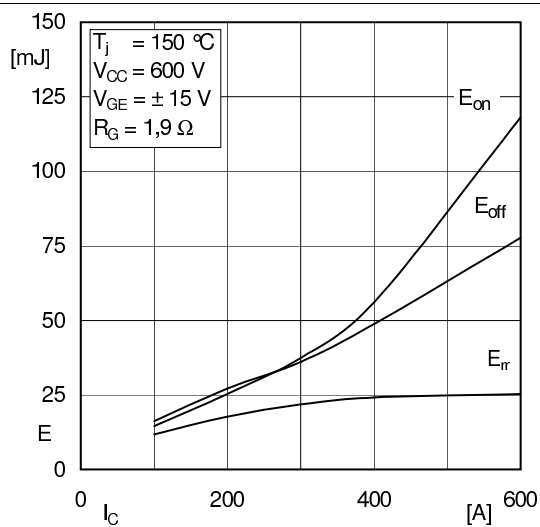


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

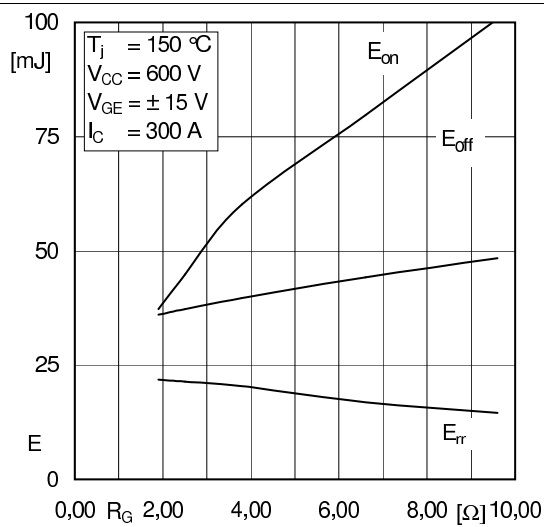


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

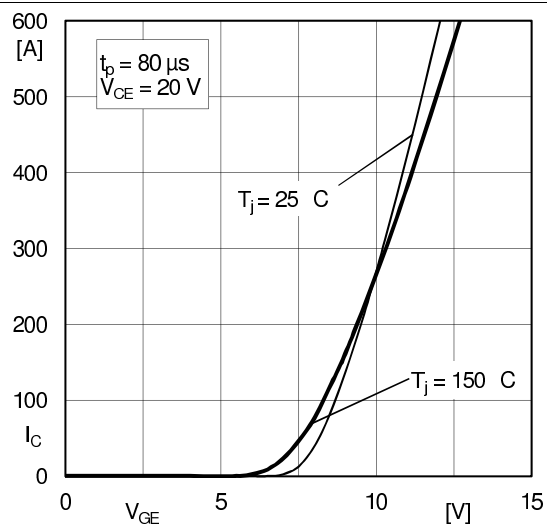


Fig. 5: Typ. transfer characteristic

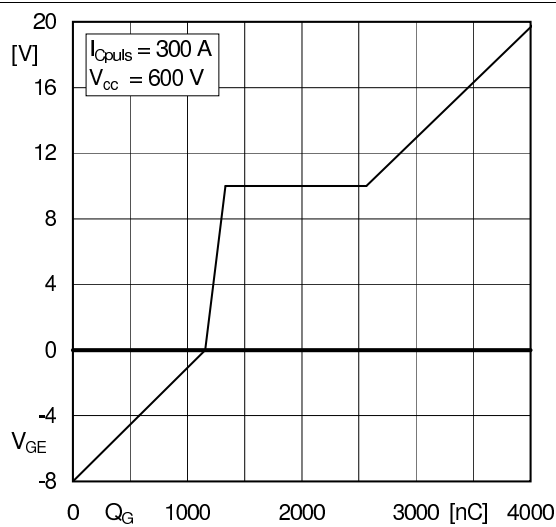
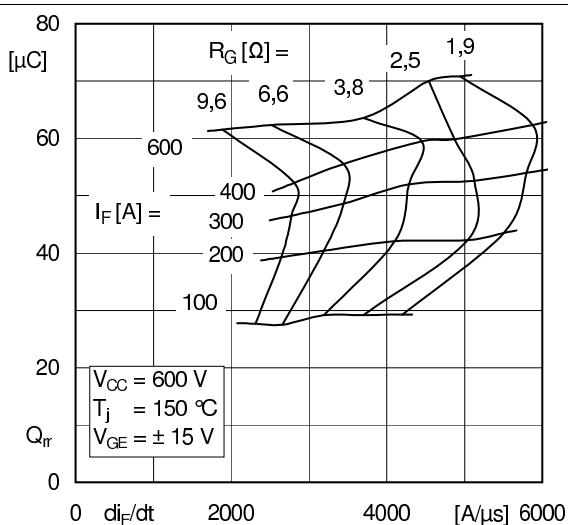
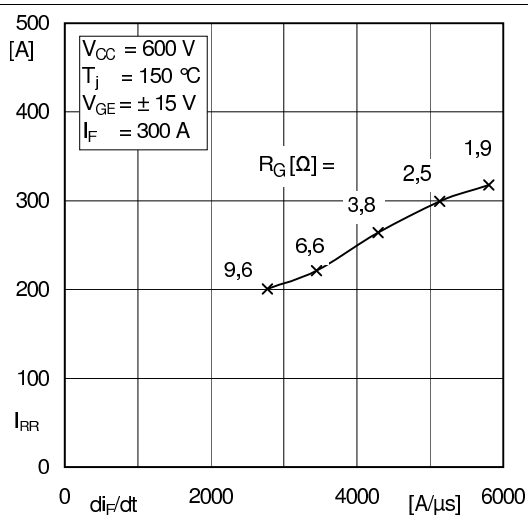
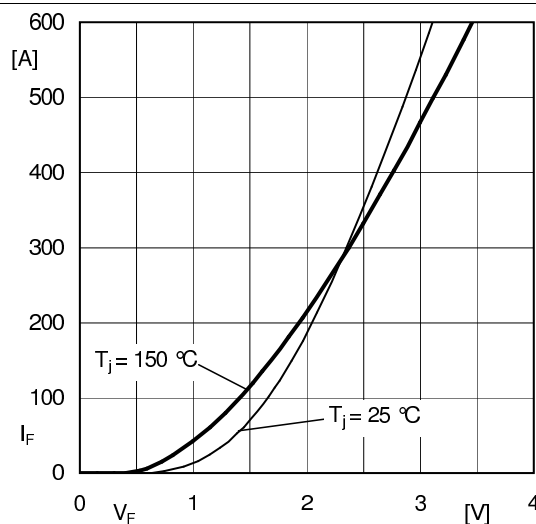
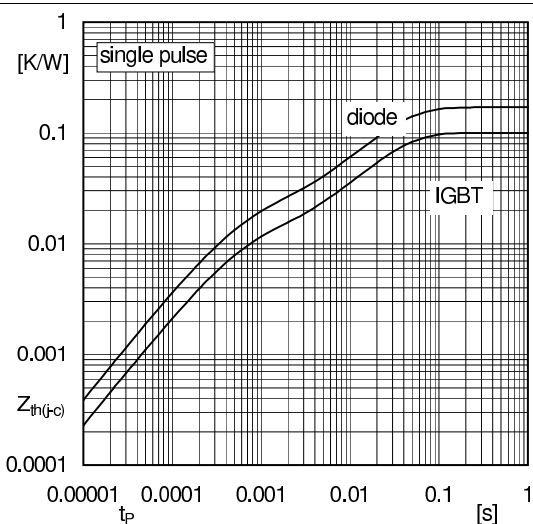
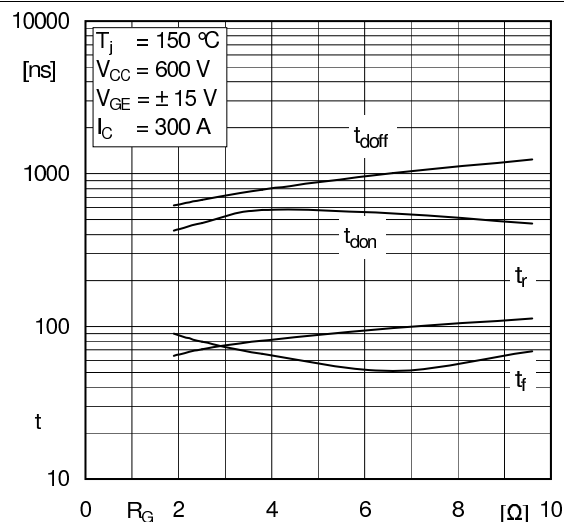
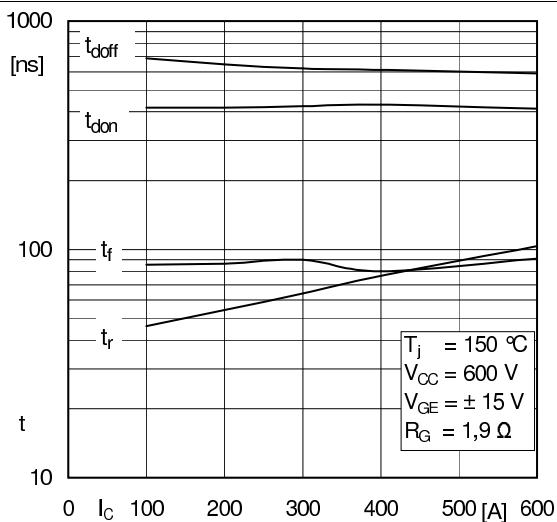


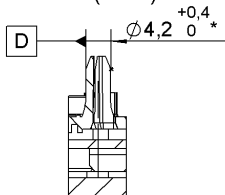
Fig. 6: Typ. gate charge characteristic



SEMiX302GB12Vs

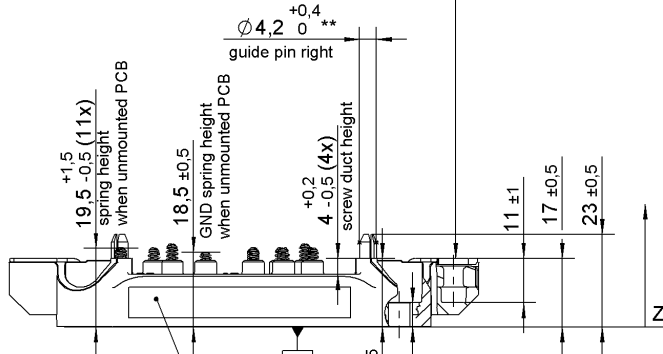
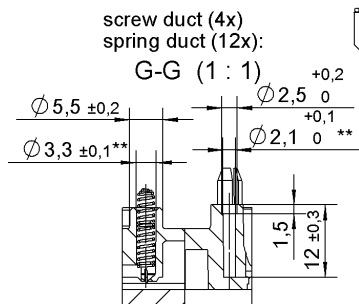


guide pin left
F-F (1 : 1)

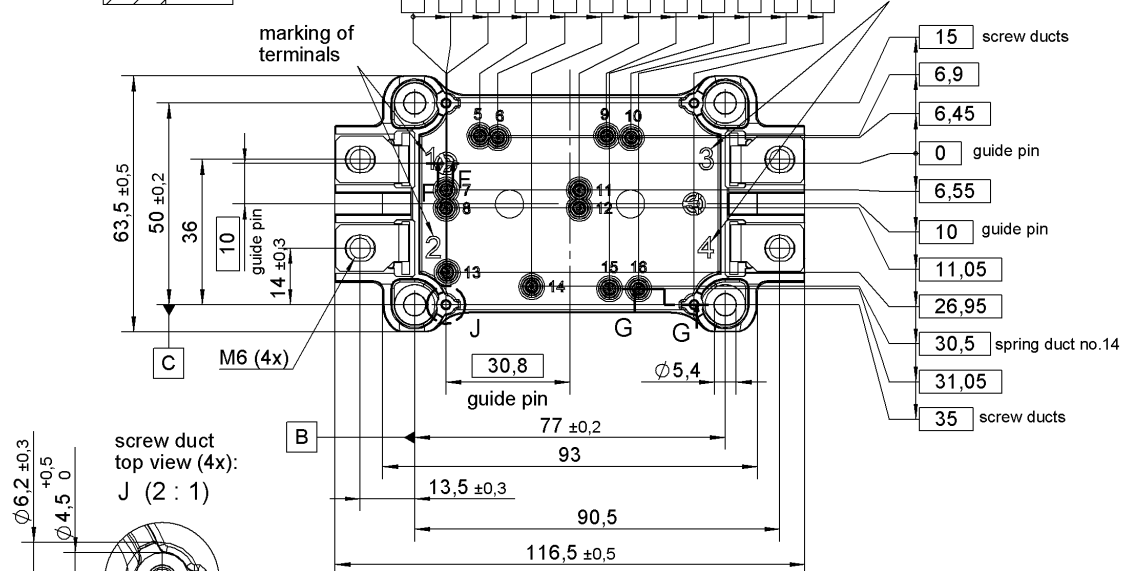
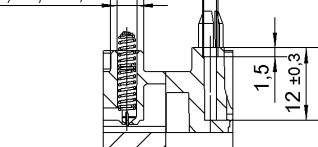


	0,3	connector 1-2 / 3-4
	0,2	each connector A

general tolerance:
ISO 2768-m
ISO 8015



All measures in Z-direction
valid when mounted to heat sink



*guide pin left with

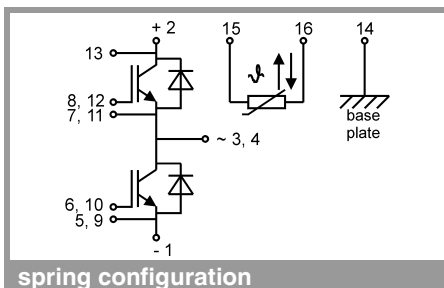
	$\varnothing$ 0,25	A	B	C
	$\varnothing$ 0,5	A	D	C

Rules for the contact PCB:

- holes guidipins = $\varnothing 4 \pm 0,1$ / position tolerance $\pm 0,1$
- holes for screws = $\varnothing 3,3 \pm 0,1$ / position tolerance $\pm 0,1$
- spring contact pad = $\varnothing 3,6 \pm 0,1$ / position tolerance $\pm 0,1$

****screw ducts / spring ducts / guide pin right with**

SEMiX 2s



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.